

AL-BASED COPPER BOARD SPECIFICATION

CCAF-05

Name: CCAF-05

Copper thickness: 35um

Insulator thickness: 150um

Board Thickness: 1.5mm

N	Item		Tech. Req.		Result
1	Peel Strength	Normality	≥ 1.8	N/mm	1.9
		260°C	≥ 1.8	N/mm	1.8
2	Blister test After Thermal stress (288°C, 2min)		No delaminating)	/	ACCEPT
3	Thermal resistance		≤ 2.0	°C/W	0.45
4	Surface Resistivity	Normality	$\geq 1 \times 10^5$	MΩ	5.0×10^7
		Constant humidity (25°C~65°C, RH: 90%~98%, 20个循环)后	$\geq 1 \times 10^5$	MΩ	4.5×10^6
5	Volume Resistivity	Normality	$\geq 1 \times 10^6$	MΩ·m	1.0×10^8
		Constant humidity (25°C~65°C, RH: 90%~98%, 20 circulations	$\geq 1 \times 10^6$	MΩ·m	1.9×10^7
6	Min Dielectric Breakdown		≥ 2	Kv	2.4
7	Dielectric constant At 1MHz (40°C, 93%, 96h)		≤ 4.4	/	2.4
8	Dielectric dissipation factor 1Mhz (40°C, 93%, 96h)		≤ 0.03	/	0.029
9	Acceleration Aging Experiment (125°C, 2000h)	Appearance	NO crimple, crack, delaminating and line Peeling)	/	ACCEPT
10	High & Low Temperature punch experiment (-50°C, 15min, 80°C, 15min15~20 circulation	Peel Strength	/	N/mm	1.39~1.64
		Surface Resistivity	/	MΩ	$1.9 \times 10^8 \sim 6.4 \times 10^8$